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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

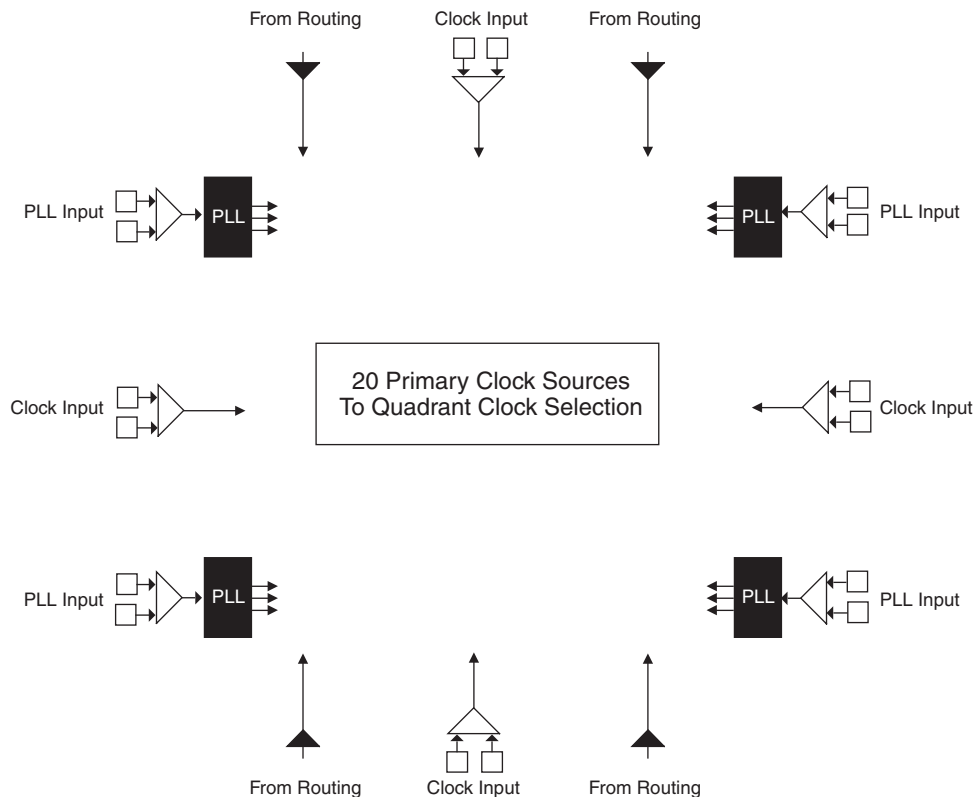
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	20000
Total RAM Bits	405504
Number of I/O	340
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp20e-5f484c

Figure 2-5. Primary Clock Sources

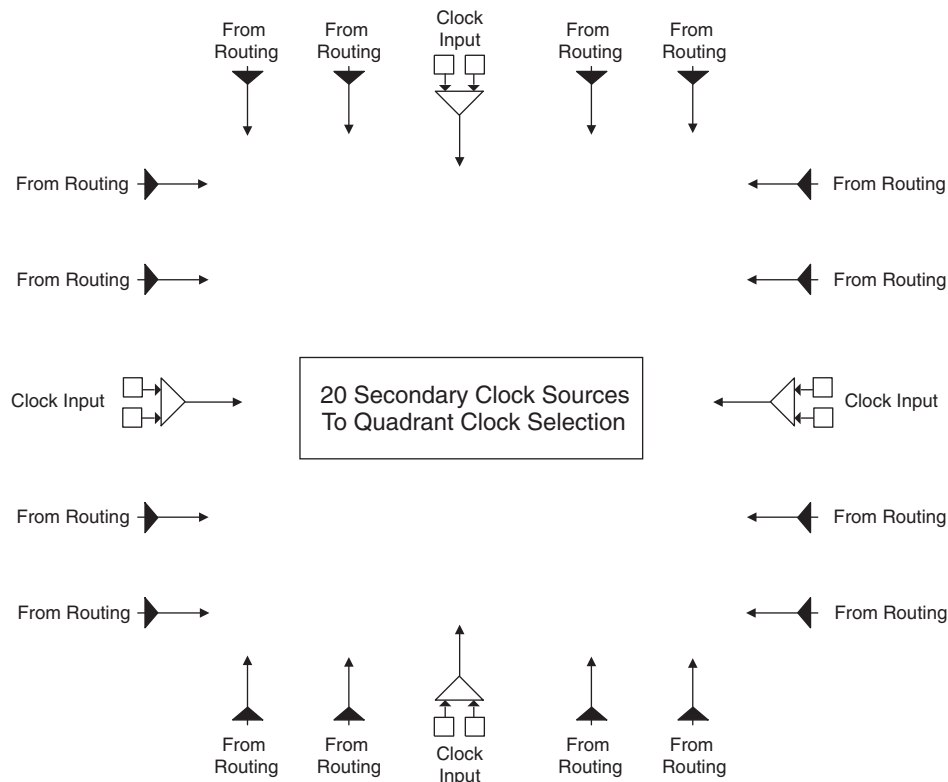


Note: Smaller devices have two PLLs.

Secondary Clock Sources

LatticeXP devices have four secondary clock resources per quadrant. The secondary clock branches are tapped at every PFU. These secondary clock networks can also be used for controls and high fanout data. These secondary clocks are derived from four clock input pads and 16 routing signals as shown in Figure 2-6.

Figure 2-6. Secondary Clock Sources



Clock Routing

The clock routing structure in LatticeXP devices consists of four Primary Clock lines and a Secondary Clock network per quadrant. The primary clocks are generated from MUXs located in each quadrant. Figure 2-7 shows this clock routing. The four secondary clocks are generated from MUXs located in each quadrant as shown in Figure 2-8. Each slice derives its clock from the primary clock lines, secondary clock lines and routing as shown in Figure 2-9.

Figure 2-7. Per Quadrant Primary Clock Selection

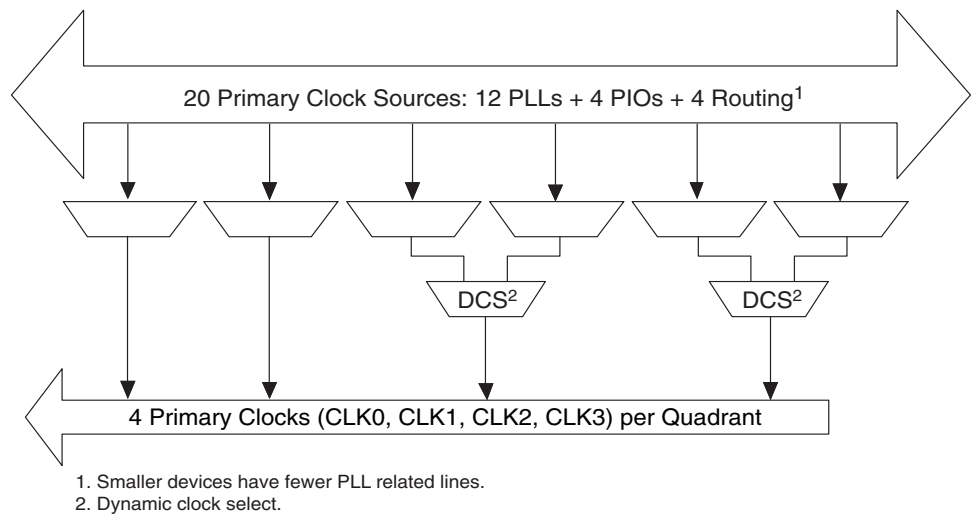
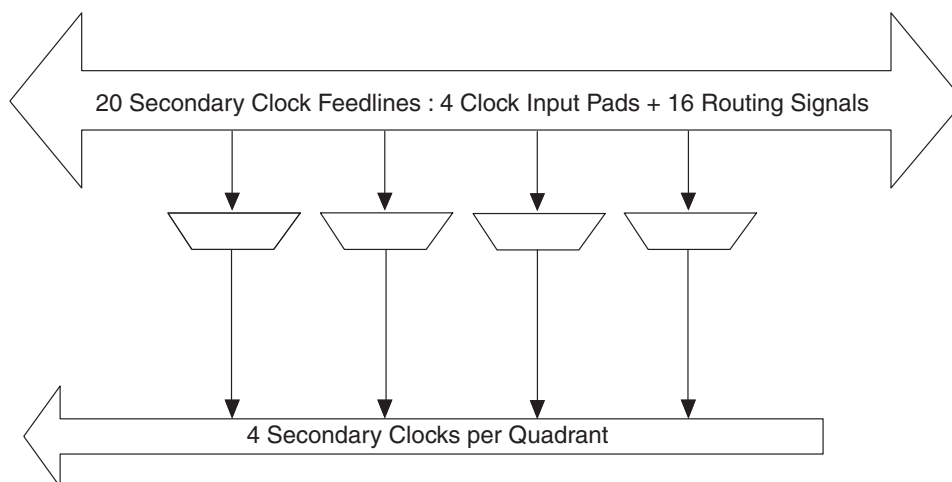
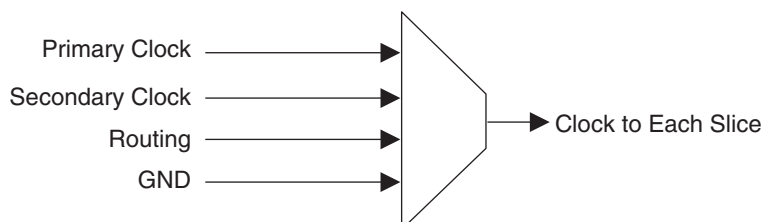


Figure 2-8. Per Quadrant Secondary Clock Selection**Figure 2-9. Slice Clock Selection**

sysCLOCK Phase Locked Loops (PLLs)

The PLL clock input, from pin or routing, feeds into an input clock divider. There are three sources of feedback signals to the feedback divider: from CLKOP (PLL internal), from clock net (CLKOP or CLKOS) or from a user clock (PIN or logic). There is a PLL_LOCK signal to indicate that VCO has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved irrespective of where the select signal is toggled. There are eight DCS blocks per device, located in pairs at the center of each side. Figure 2-12 illustrates the DCS Block Macro.

Figure 2-12. DCS Block Primitive

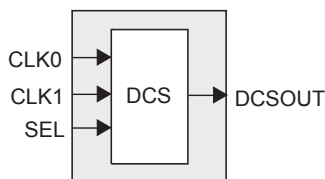
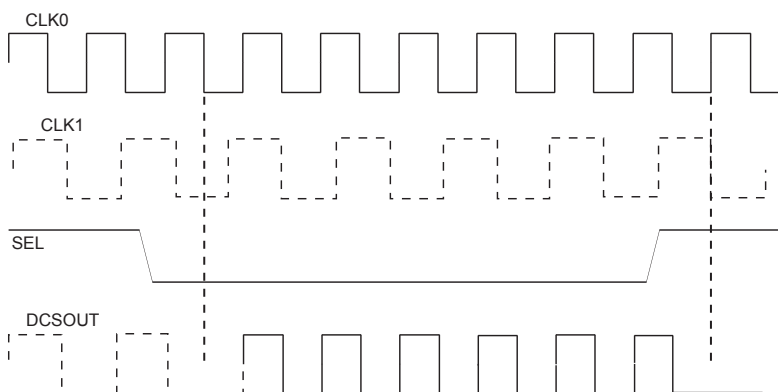


Figure 2-13 shows timing waveforms of the default DCS operating mode. The DCS block can be programmed to other modes. For more information on the DCS, please see details of additional technical documentation at the end of this data sheet.

Figure 2-13. DCS Waveforms



sysMEM Memory

The LatticeXP family of devices contain a number of sysMEM Embedded Block RAM (EBR). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Memory Cascading

Larger and deeper blocks of RAMs can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual and Pseudo-Dual Port Modes

Figure 2-14 shows the four basic memory configurations and their input/output names. In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output.

Figure 2-18. Group of Seven PIOs

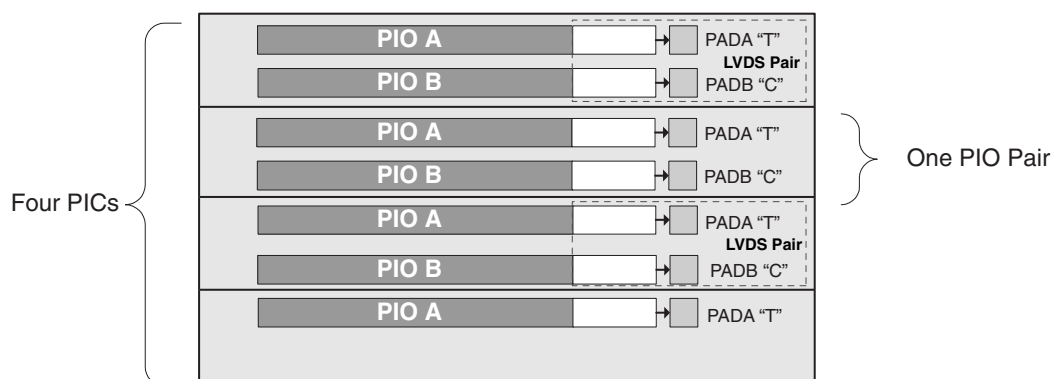
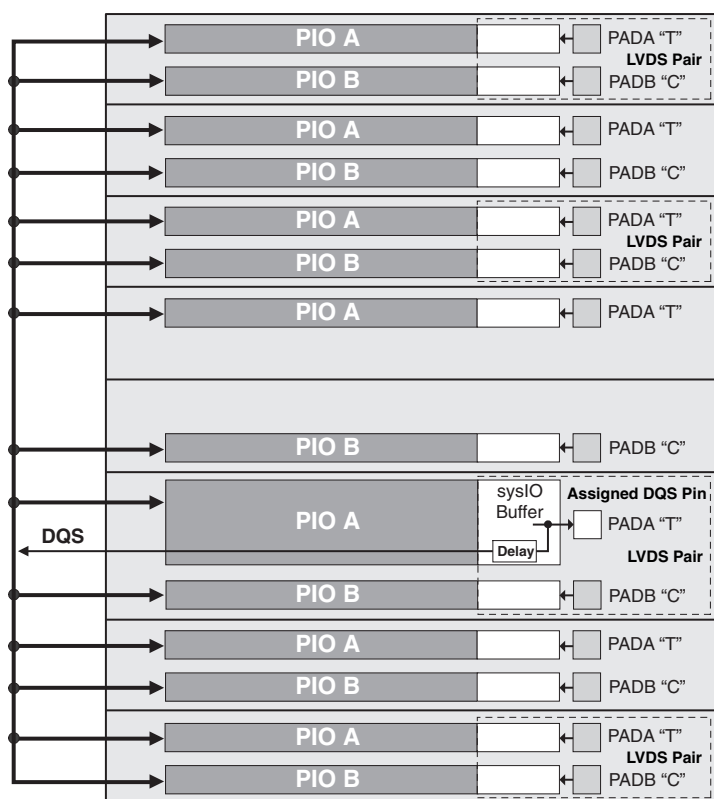


Figure 2-19. DQS Routing



PIO

The PIO contains four blocks: an input register block, output register block, tristate register block and a control logic block. These blocks contain registers for both single data rate (SDR) and double data rate (DDR) operation along with the necessary clock and selection logic. Programmable delay lines used to shift incoming clock and data signals are also included in these blocks.

Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-20 shows the diagram of the input register block.

Input signals are fed from the sysIO buffer to the input register block (as signal DI). If desired the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and

In selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, ensures no positive input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-21 shows the input register waveforms for DDR operation and Figure 2-22 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal **DDRCLKPOL** controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the **DQS** to the system clock domain. For further discussion of this topic, see the **DDR memory** section of this data sheet.

Figure 2-20. Input Register Diagram

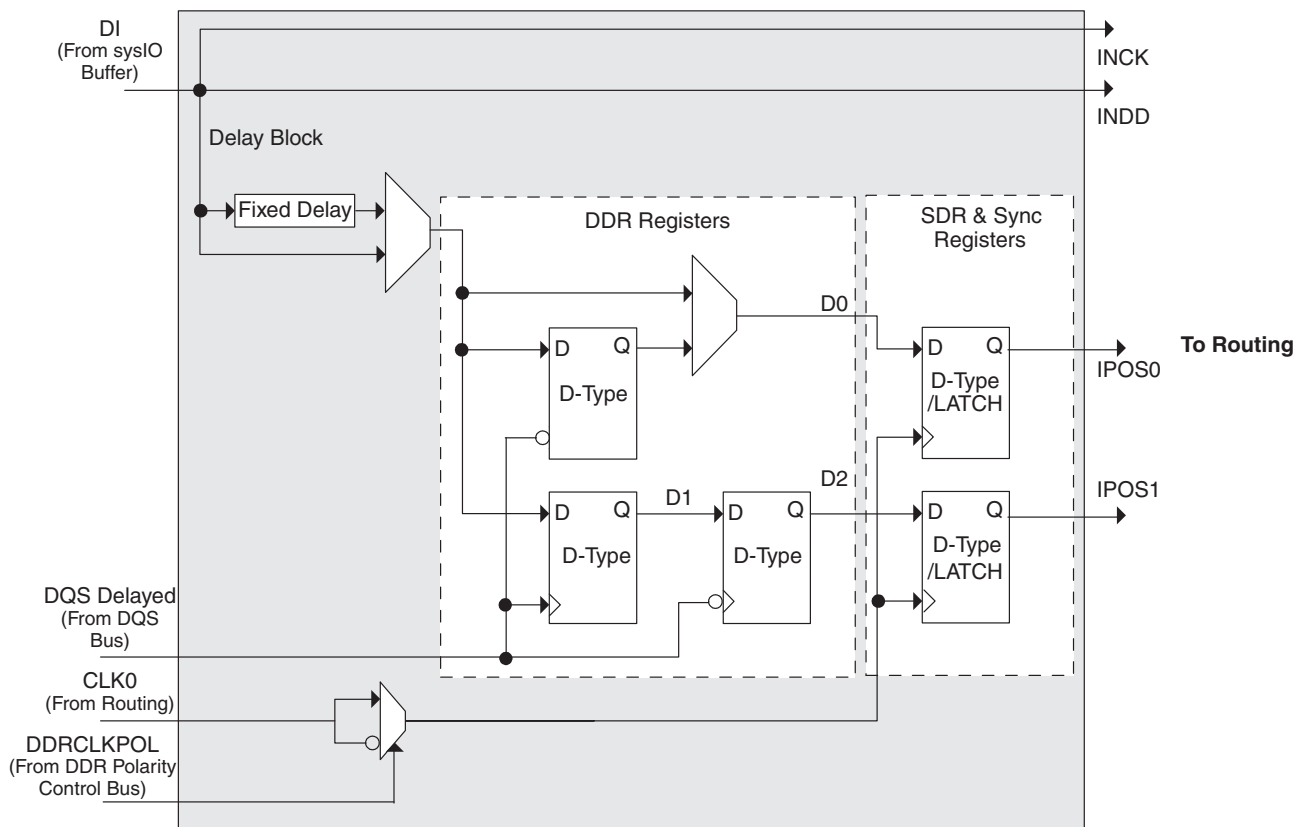
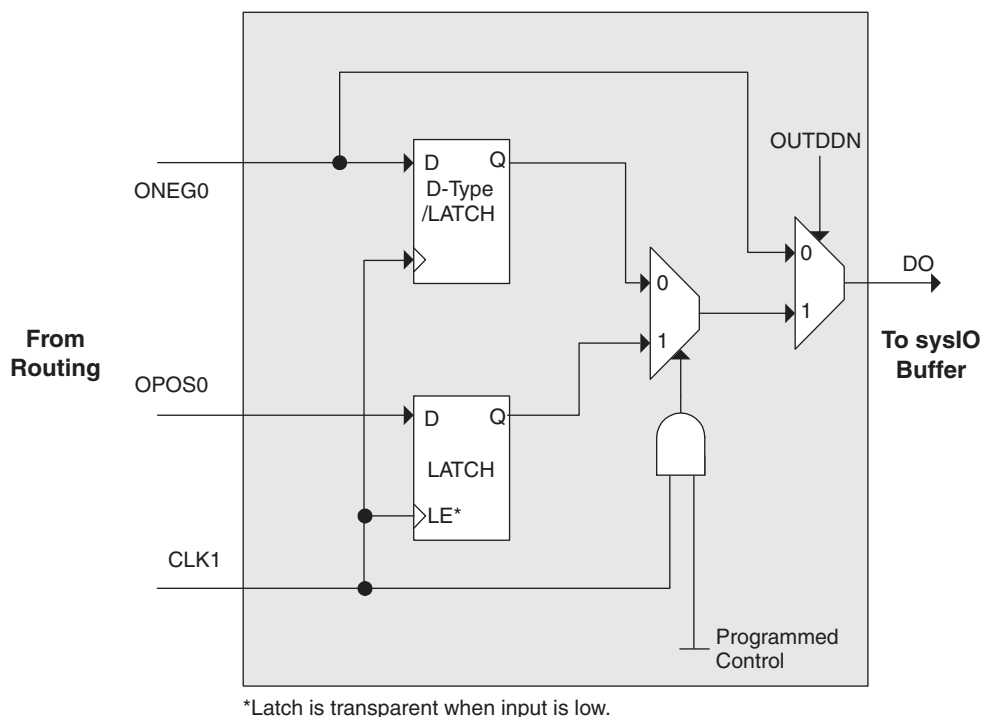
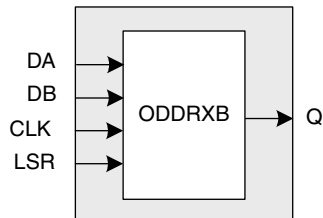


Figure 2-23. Output Register Block**Figure 2-24. ODDRXB Primitive****Tristate Register Block**

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-25 shows the diagram of the Tristate Register Block.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 is fed into one register on the positive edge of the clock and OPOS1 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-29 provides a pictorial representation of the different programming ports and modes available in the LatticeXP devices.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port.

Leave Alone I/O

When using 1532 mode for non-volatile memory programming, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

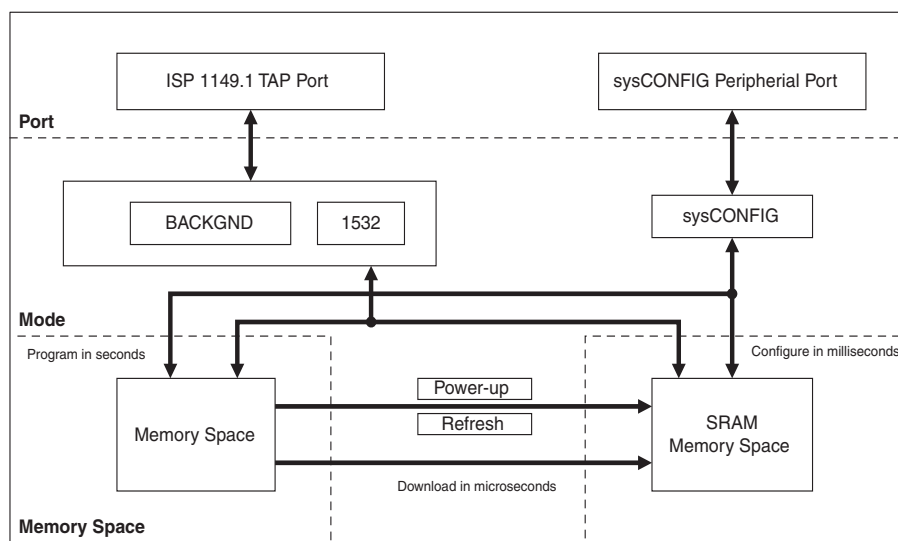
TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See Lattice technical note #TN1087, *Minimizing System Interruption During Configuration Using TransFR Technology*, for details.

Security

The LatticeXP devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Figure 2-29. ispXP Block Diagram



Internal Logic Analyzer Capability (ispTRACY)

All LatticeXP devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time.

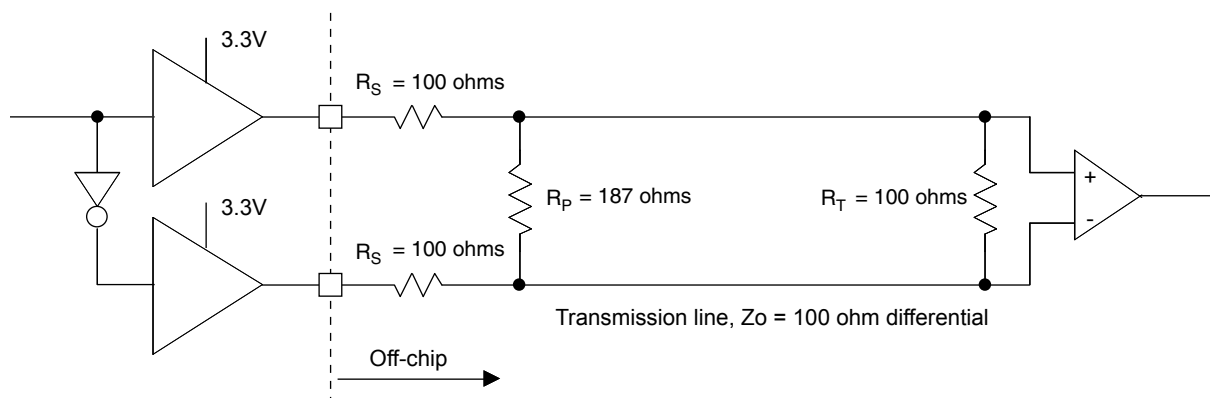
For more information on ispTRACY, please see information regarding additional technical documentation at the end of this data sheet.

Oscillator

Every LatticeXP device has an internal CMOS oscillator which is used to derive a master serial clock for configuration. The oscillator and the master serial clock run continuously in the configuration mode. The default value of the

LVPECL

The LatticeXP devices support differential LVPECL standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL**Table 3-3. LVPECL DC Conditions¹****Over Recommended Operating Conditions**

Symbol	Description	Typical	Units
Z_{OUT}	Output impedance	100	ohms
R_P	Driver parallel resistor	187	ohms
R_S	Driver series resistor	100	ohms
R_T	Receiver termination	100	ohms
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	85.7	ohms
I_{DC}	DC output current	12.7	mA

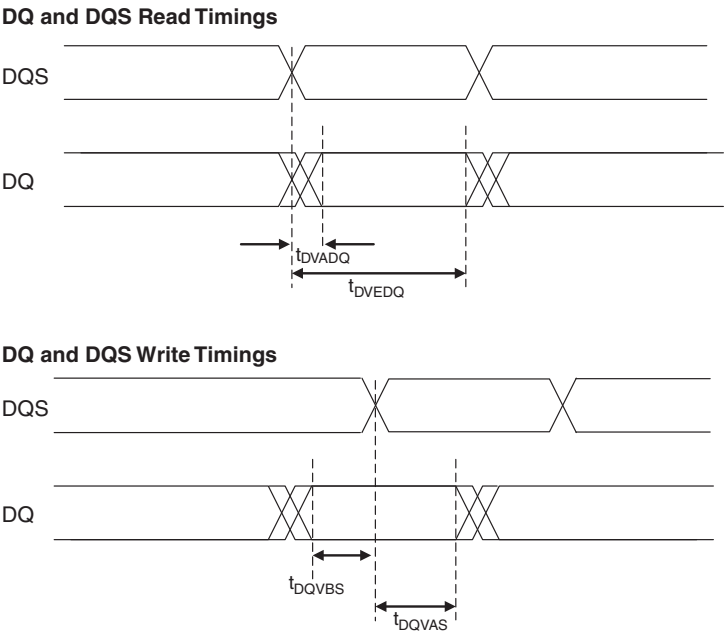
1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The LatticeXP devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-5. DDR Timings



LatticeXP Family Timing Adders¹ (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_I	HSTL_15 class I	0.2	0.2	0.2	ns
HSTL15_III	HSTL_15 class III	0.2	0.2	0.2	ns
HSTL15D_I	Differential HSTL 15 class I	0.2	0.2	0.2	ns
HSTL15D_III	Differential HSTL 15 class III	0.2	0.2	0.2	ns
SSTL33_I	SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33_II	SSTL_3 class II	0.3	0.3	0.3	ns
SSTL33D_I	Differential SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33D_II	Differential SSTL_3 class II	0.3	0.3	0.3	ns
SSTL25_I	SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25_II	SSTL_2 class II	0.3	0.3	0.3	ns
SSTL25D_I	Differential SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25D_II	Differential SSTL_2 class II	0.3	0.3	0.3	ns
SSTL18_I	SSTL_1.8 class I	0.1	0.1	0.1	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.1	0.1	0.1	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.8	0.8	0.8	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.5	0.5	0.5	ns
LVTTTL33_12mA	LVTTTL 12mA drive	0.3	0.3	0.3	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.4	0.4	0.4	ns
LVTTTL33_20mA	LVTTTL 20mA drive	0.3	0.3	0.3	ns
LVC MOS33_2mA	LVC MOS 3.3 2mA drive	0.8	0.8	0.8	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.8	0.8	0.8	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.5	0.5	0.5	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	0.3	0.3	0.3	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive	0.4	0.4	0.4	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive	0.3	0.3	0.3	ns
LVC MOS25_2mA	LVC MOS 2.5 2mA drive	0.7	0.7	0.7	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.7	0.7	0.7	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.4	0.4	0.4	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.0	0.0	0.0	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive	0.2	0.2	0.2	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive	0.4	0.4	0.4	ns
LVC MOS18_2mA	LVC MOS 1.8 2mA drive	0.6	0.6	0.6	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.6	0.6	0.6	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.4	0.4	0.4	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	0.2	0.2	0.2	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive	0.2	0.2	0.2	ns
LVC MOS15_2mA	LVC MOS 1.5 2mA drive	0.6	0.6	0.6	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.6	0.6	0.6	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.2	0.2	0.2	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.4	0.4	0.4	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.4	0.4	0.4	ns
PCI33	PCI33	0.3	0.3	0.3	ns

1. General timing numbers based on LVC MOS 2.5, 12mA.
Timing v.F0.11

LFXP3 Logic Signal Connections: 100 TQFP

Pin Number	Pin Function	Bank	Differential	Dual Function
1	CFG1	0	-	-
2	DONE	0	-	-
3	PROGRAMN	7	-	-
4	CCLK	7	-	-
5	PL3A	7	T	LUM0_PLLT_FB_A
6	PL3B	7	C	LUM0_PLLC_FB_A
7	VCCIO7	7	-	-
8	PL5A	7	-	VREF1_7
9	PL6B	7	-	VREF2_7
10	GNDIO7	7	-	-
11	PL7A	7	T ³	DQS
12	PL7B	7	C ³	-
13	PL8A	7	T	LUM0_PLLT_IN_A
14	PL8B	7	C	LUM0_PLLC_IN_A
15	PL9A	7	T ³	-
16	PL9B	7	C ³	-
17	VCCP0	-	-	-
18	GNDP0	-	-	-
19	PL12A	6	T	PCLKT6_0
20	PL12B	6	C	PCLKC6_0
21	GNDIO6	6	-	-
22	VCCIO6	6	-	-
23	PL18A	6	T ³	-
24	PL18B	6	C ³	-
25	VCCAUX	-	-	-
26	SLEEPN ¹ /TOE ²	-	-	-
27	INITN	5	-	-
28	VCC	-	-	-
29	PB2B	5	-	VREF1_5
30	PB5B	5	-	VREF2_5
31	PB8A	5	T	-
32	PB8B	5	C	-
33	GNDIO5	5	-	-
34	PB9A	5	-	-
35	PB10B	5	-	-
36	PB11A	5	T	DQS
37	PB11B	5	C	-
38	VCCIO5	5	-	-
39	PB12A	5	T	-
40	PB12B	5	C	-
41	PB13A	5	T	-
42	PB13B	5	C	-
43	GND	-	-	-

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L15	PR21B	3	C ³	-	PR28B	3	C ³	-
L14	PR21A	3	T ³	-	PR28A	3	T ³	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
L12	PR17B	3	C	-	PR26A	3	-	-
M16	PR20B	3	C	-	PR25B	3	C	RLM0_PLLC_IN_A
N16	PR20A	3	T	-	PR25A	3	T	RLM0_PLLT_IN_A
K14	PR19B	3	C ³	-	PR24B	3	C ³	-
K15	PR19A	3	T ³	-	PR24A	3	T ³	DQS
K12	PR17A	3	T	-	PR23B	3	-	-
K13	PR22A	3	-	VREF2_3	PR22A	3	-	VREF2_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
L16	PR18B	3	C ³	-	PR21B	3	C ³	-
K16	PR18A	3	T ³	-	PR21A	3	T ³	-
J15	PR16B	3	C ³	-	PR19B	3	C ³	-
J14	PR16A	3	T ³	-	PR19A	3	T ³	-
J13	GNDP1	-	-	-	GNDP1	-	-	-
J12	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J16	PR12B	2	C	PCLKC2_0	PR17B	2	C	PCLKC2_0
H16	PR12A	2	T	PCLKT2_0	PR17A	2	T	PCLKT2_0
H13	PR13B	2	C ³	-	PR16B	2	C ³	-
H12	PR13A	2	T ³	-	PR16A	2	T ³	DQS
H15	PR2B	2	C ³	-	PR15B	2	-	-
H14	PR6B	2	-	VREF1_2	PR14A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G15	PR11B	2	C ³	-	PR13B	2	C ³	-
G14	PR11A	2	T ³	-	PR13A	2	T ³	-
G16	PR8B	2	C	RUM0_PLLC_IN_A	PR12B	2	C	RUM0_PLLC_IN_A
F16	PR8A	2	T	RUM0_PLLT_IN_A	PR12A	2	T	RUM0_PLLT_IN_A
G13	PR2A	2	T ³	-	PR11B	2	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G12	PR9B	2	C ³	-	PR8B	2	C	-
F13	PR9A	2	T ³	-	PR8A	2	T	-
B16	PR7B	2	C ³	-	PR7B	2	C ³	-
C16	PR7A	2	T ³	DQS	PR7A	2	T ³	DQS
F15	PR14A	2	-	-	PR6B	2	-	-
E15	PR5A	2	-	VREF2_2	PR5A	2	-	VREF2_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F14	PR4B	2	C ³	-	PR4B	2	C ³	-
E14	PR4A	2	T ³	-	PR4A	2	T ³	-
D15	PR3B	2	C	RUM0_PLLC_FB_A	PR3B	2	C	RUM0_PLLC_FB_A
C15	PR3A	2	T	RUM0_PLLT_FB_A	PR3A	2	T	RUM0_PLLT_FB_A

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
E8	PT13B	0	-	-	PT17B	0	-	-
D8	PT12A	0	-	DOUT	PT16A	0	-	DOUT
A6	PT11B	0	C	-	PT15B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C6	PT11A	0	T	WRITEN	PT15A	0	T	WRITEN
E7	PT10B	0	C	-	PT14B	0	C	-
D7	PT10A	0	T	VREF1_0	PT14A	0	T	VREF1_0
A5	PT9B	0	C	-	PT13B	0	C	-
B5	PT9A	0	T	DI	PT13A	0	T	DI
A4	PT8B	0	C	-	PT12B	0	C	-
B6	PT8A	0	T	CSN	PT12A	0	T	CSN
E6	PT7B	0	C	-	PT11B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
D6	PT7A	0	T	-	PT11A	0	T	-
D5	PT6B	0	C	VREF2_0	PT10B	0	C	VREF2_0
A3	PT6A	0	T	DQS	PT10A	0	T	DQS
B3	PT5B	0	-	-	PT9B	0	-	-
B2	PT4A	0	-	-	PT8A	0	-	-
A2	PT3B	0	C	-	PT7B	0	C	-
B1	PT3A	0	T	-	PT7A	0	T	-
F5	PT2B	0	C	-	PT6B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C5	PT2A	0	T	-	PT6A	0	T	-
C4	CFG0	0	-	-	CFG0	0	-	-
B4	CFG1	0	-	-	CFG1	0	-	-
C3	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-
A16	GND	-	-	-	GND	-	-	-
F11	GND	-	-	-	GND	-	-	-
F6	GND	-	-	-	GND	-	-	-
G10	GND	-	-	-	GND	-	-	-
G7	GND	-	-	-	GND	-	-	-
G8	GND	-	-	-	GND	-	-	-
G9	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-
H7	GND	-	-	-	GND	-	-	-
H8	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J7	GND	-	-	-	GND	-	-	-
J8	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
T6	PL41A	6	T	-	PL45A	6	T	-
T5	PL41B	6	C	-	PL45B	6	C	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
U3	PL42A	6	T ³	-	PL46A	6	T ³	-
U4	PL42B	6	C ³	-	PL46B	6	C ³	-
V4	PL43A	6	-	-	PL47A	6	-	-
W4	SLEEPN ¹ / TOE ²	-	-	-	SLEEPN ¹ / TOE ²	-	-	-
W5	INITN	5	-	-	INITN	5	-	-
Y3	-	-	-	-	PB3B	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
U5	-	-	-	-	PB4A	5	T	-
V5	-	-	-	-	PB4B	5	C	-
Y4	-	-	-	-	PB5A	5	T	-
Y5	-	-	-	-	PB5B	5	C	-
V6	-	-	-	-	PB6A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
U6	-	-	-	-	PB6B	5	C	-
W6	PB3A	5	T	-	PB7A	5	T	-
Y6	PB3B	5	C	-	PB7B	5	C	-
AA2	PB4A	5	T	-	PB8A	5	T	-
AA3	PB4B	5	C	-	PB8B	5	C	-
V7	PB5A	5	-	-	PB9A	5	-	-
U7	PB6B	5	-	-	PB10B	5	-	-
Y7	PB7A	5	T	DQS	PB11A	5	T	DQS
W7	PB7B	5	C	-	PB11B	5	C	-
AA4	PB8A	5	T	-	PB12A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA5	PB8B	5	C	-	PB12B	5	C	-
AB3	PB9A	5	T	-	PB13A	5	T	-
AB4	PB9B	5	C	-	PB13B	5	C	-
AA6	PB10A	5	T	-	PB14A	5	T	-
AA7	PB10B	5	C	-	PB14B	5	C	-
U8	PB11A	5	T	-	PB15A	5	T	-
V8	PB11B	5	C	-	PB15B	5	C	-
Y8	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
W8	PB12B	5	C	-	PB16B	5	C	-
V9	PB13A	5	-	-	PB17A	5	-	-
U9	PB14B	5	-	-	PB18B	5	-	-
Y9	PB15A	5	T	DQS	PB19A	5	T	DQS
W9	PB15B	5	C	-	PB19B	5	C	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
R18	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
R17	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A
Y22	PR37B	3	C ³	-	PR41B	3	C ³	-
Y21	PR37A	3	T ³	DQS	PR41A	3	T ³	DQS
W22	PR36B	3	-	-	PR40B	3	-	-
W21	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
P17	PR34B	3	C ³	-	PR38B	3	C ³	-
P18	PR34A	3	T ³	-	PR38A	3	T ³	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
R19	PR33B	3	C	-	PR37B	3	C	-
R20	PR33A	3	T	-	PR37A	3	T	-
V22	PR32B	3	C ³	-	PR36B	3	C ³	-
V21	PR32A	3	T ³	-	PR36A	3	T ³	-
U22	PR30B	3	C ³	-	PR34B	3	C ³	-
U21	PR30A	3	T ³	-	PR34A	3	T ³	-
P19	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
P20	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
T22	PR28B	3	C ³	-	PR32B	3	C ³	-
T21	PR28A	3	T ³	DQS	PR32A	3	T ³	DQS
R22	PR27B	3	-	-	PR31B	3	-	-
R21	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
N19	PR25B	3	C ³	-	PR29B	3	C ³	-
N20	PR25A	3	T ³	-	PR29A	3	T ³	-
N18	PR24B	3	C	-	PR28B	3	C	-
M18	PR24A	3	T	-	PR28A	3	T	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P22	PR23B	3	C ³	-	PR27B	3	C ³	-
P21	PR23A	3	T ³	-	PR27A	3	T ³	-
N22	-	-	-	-	PR26B	3	C ³	-
N21	-	-	-	-	PR26A	3	T ³	-
M19	-	-	-	-	PR25B	3	-	-
M20	GNDP1	-	-	-	GNDP1	-	-	-
L18	VCCP1	-	-	-	VCCP1	-	-	-
M21	-	-	-	-	PR24A	2	-	-
M22	PR22B	2	C ³	-	PR23B	2	C ³	-
L22	PR22A	2	T ³	-	PR23A	2	T ³	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
L19	-	-	-	-	PR22B	2	C ³	-
L20	-	-	-	-	PR22A	2	T ³	-
L21	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
K22	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
A14	PT30B	1	-	-	PT34B	1	-	-
B14	PT29A	1	-	D4	PT33A	1	-	D4
C12	PT28B	1	C	-	PT32B	1	C	-
B12	PT28A	1	T	D5	PT32A	1	T	D5
-	GNDIO1	1	-	-	GNDIO1	1	-	-
D12	PT27B	1	C	D6	PT31B	1	C	D6
E12	PT27A	1	T	-	PT31A	1	T	-
A13	PT26B	1	C	D7	PT30B	1	C	D7
A12	PT26A	1	T	-	PT30A	1	T	-
A11	PT25B	0	C	BUSY	PT29B	0	C	BUSY
-	GNDIO0	0	-	-	GNDIO0	0	-	-
A10	PT25A	0	T	CS1N	PT29A	0	T	CS1N
D11	PT24B	0	C	PCLKC0_0	PT28B	0	C	PCLKC0_0
E11	PT24A	0	T	PCLKT0_0	PT28A	0	T	PCLKT0_0
B11	PT23B	0	C	-	PT27B	0	C	-
C11	PT23A	0	T	DQS	PT27A	0	T	DQS
B9	PT22B	0	-	-	PT26B	0	-	-
A9	PT21A	0	-	DOUT	PT25A	0	-	DOUT
B8	PT20B	0	C	-	PT24B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
A8	PT20A	0	T	WRITEN	PT24A	0	T	WRITEN
E10	PT19B	0	C	-	PT23B	0	C	-
D10	PT19A	0	T	VREF1_0	PT23A	0	T	VREF1_0
C10	PT18B	0	C	-	PT22B	0	C	-
B10	PT18A	0	T	DI	PT22A	0	T	DI
B7	PT17B	0	C	-	PT21B	0	C	-
A7	PT17A	0	T	CSN	PT21A	0	T	CSN
C9	PT16B	0	C	-	PT20B	0	C	-
D9	PT16A	0	T	-	PT20A	0	T	-
B6	PT15B	0	C	VREF2_0	PT19B	0	C	VREF2_0
A6	PT15A	0	T	DQS	PT19A	0	T	DQS
F9	PT14B	0	-	-	PT18B	0	-	-
E9	PT13A	0	-	-	PT17A	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
B5	PT12B	0	C	-	PT16B	0	C	-
A5	PT12A	0	T	-	PT16A	0	T	-
C8	PT11B	0	C	-	PT15B	0	C	-
D8	PT11A	0	T	-	PT15A	0	T	-
B4	PT10B	0	C	-	PT14B	0	C	-
A4	PT10A	0	T	-	PT14A	0	T	-
F8	PT9B	0	C	-	PT13B	0	C	-
E8	PT9A	0	T	-	PT13A	0	T	-

Conventional Packaging**Commercial**

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3Q208C	136	1.8/2.5/3.3V	-3	PQFP	208	COM	3.1K
LFXP3C-4Q208C	136	1.8/2.5/3.3V	-4	PQFP	208	COM	3.1K
LFXP3C-5Q208C	136	1.8/2.5/3.3V	-5	PQFP	208	COM	3.1K
LFXP3C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	3.1K
LFXP3C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	3.1K
LFXP3C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	3.1K
LFXP3C-3T100C	62	1.8/2.5/3.3V	-3	TQFP	100	COM	3.1K
LFXP3C-4T100C	62	1.8/2.5/3.3V	-4	TQFP	100	COM	3.1K
LFXP3C-5T100C	62	1.8/2.5/3.3V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	5.8K
LFXP6C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	5.8K
LFXP6C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	5.8K
LFXP6C-3Q208C	142	1.8/2.5/3.3V	-3	PQFP	208	COM	5.8K
LFXP6C-4Q208C	142	1.8/2.5/3.3V	-4	PQFP	208	COM	5.8K
LFXP6C-5Q208C	142	1.8/2.5/3.3V	-5	PQFP	208	COM	5.8K
LFXP6C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	5.8K
LFXP6C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	5.8K
LFXP6C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3F388C	244	1.8/2.5/3.3V	-3	fpBGA	388	COM	9.7K
LFXP10C-4F388C	244	1.8/2.5/3.3V	-4	fpBGA	388	COM	9.7K
LFXP10C-5F388C	244	1.8/2.5/3.3V	-5	fpBGA	388	COM	9.7K
LFXP10C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	9.7K
LFXP10C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	9.7K
LFXP10C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	9.7K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3F484I	300	1.8/2.5/3.3V	-3	fpBGA	484	IND	15.5K
LFXP15C-4F484I	300	1.8/2.5/3.3V	-4	fpBGA	484	IND	15.5K
LFXP15C-3F388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	15.5K
LFXP15C-4F388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	15.5K
LFXP15C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	15.5K
LFXP15C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3F484I	340	1.8/2.5/3.3V	-3	fpBGA	484	IND	19.7K
LFXP20C-4F484I	340	1.8/2.5/3.3V	-4	fpBGA	484	IND	19.7K
LFXP20C-3F388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	19.7K
LFXP20C-4F388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	19.7K
LFXP20C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	19.7K
LFXP20C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3Q208I	136	1.2V	-3	PQFP	208	IND	3.1K
LFXP3E-4Q208I	136	1.2V	-4	PQFP	208	IND	3.1K
LFXP3E-3T144I	100	1.2V	-3	TQFP	144	IND	3.1K
LFXP3E-4T144I	100	1.2V	-4	TQFP	144	IND	3.1K
LFXP3E-3T100I	62	1.2V	-3	TQFP	100	IND	3.1K
LFXP3E-4T100I	62	1.2V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3F256I	188	1.2V	-3	fpBGA	256	IND	5.8K
LFXP6E-4F256I	188	1.2V	-4	fpBGA	256	IND	5.8K
LFXP6E-3Q208I	142	1.2V	-3	PQFP	208	IND	5.8K
LFXP6E-4Q208I	142	1.2V	-4	PQFP	208	IND	5.8K
LFXP6E-3T144I	100	1.2V	-3	TQFP	144	IND	5.8K
LFXP6E-4T144I	100	1.2V	-4	TQFP	144	IND	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3F388I	244	1.2V	-3	fpBGA	388	IND	9.7K
LFXP10E-4F388I	244	1.2V	-4	fpBGA	388	IND	9.7K
LFXP10E-3F256I	188	1.2V	-3	fpBGA	256	IND	9.7K
LFXP10E-4F256I	188	1.2V	-4	fpBGA	256	IND	9.7K